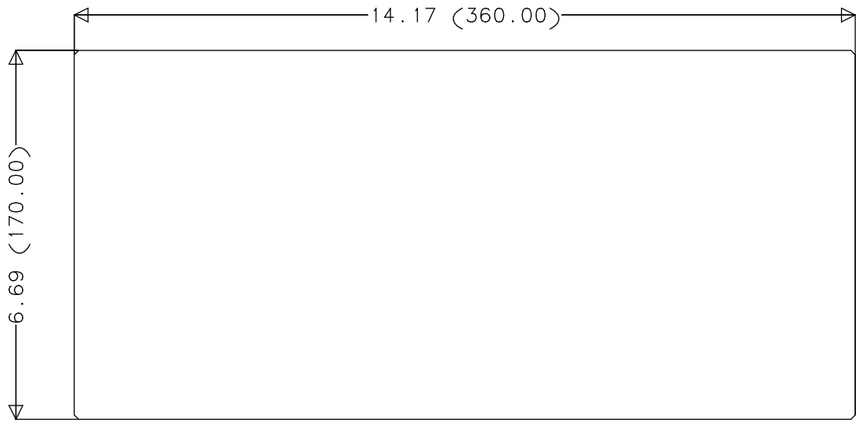
# BOARD SPECIFICATIONS

A-2920 Board Size  Unit: Inch (mm)




1. Board Layers: 10
2. Layer Stack Order:

| | |
|---|---|
| Layer1/Artwork_1: | Top Signal Layer (signal_1) (0.5 oz) |
| Layer2/Artwork_2: | Ground Layer, (0.5 oz) |
| Layer3/Artwork_3: | P1V2, Power_2, (0.5 oz) |
| Layer4/Artwork_4: | Inner_signal_3 (0.5 oz) |
| Layer5/Artwork_5: | Inner_signal_4 (0.5oz) |
| Layer6/Artwork_6: | P2V5, Power_3, 0.5 oz. |
| Layer7/Artwork_7: | Inner_signal_5 (0.5oz) |
| Layer8/Artwork_8: | Inner_signal_6 (0.5oz) |
| Layer9/Artwork_9: | P3V3, Power_4, (0.5 oz) |
| Layer10/Artwork_10: | Bottom Signal Layer(Signal_2) (0.5 oz) |

3. Apply silkscreen on both side:
   Artwork_7: Top silkscreen.
   Artwork_8: Bottom silkscreen
4. Apply solder mask over bare copper on both side:
   Artwork_9:  Top solder mask
   Artwork_10: Bottom solde mask
5. Material: FR4
6. Board thickness: 0.072'' +/- 0.010.
7. TRACE IMPEDENCE:  50 ohms +/- 10%.
10. Copper thickness 0.5oz before plating for all layers.
11. Immersion gold plating (3 to 8 micro-inches soft gold) over bare copper
12. All layers laid out in mininum trace width/clearence 0.005"/0.005"
13. All dimensions are in inches unless otherwise noted.

BOARD's DRILL SCHEDULE (Inch)

| DRILL SYMBOL | DRILL SIZE | COUNT | PLATED | Min/Max |
|---|---|---|---|---|
| ○ | .008 | 588 | YES | --- |
| ⊞ | .01 | 324 | YES | --- |
| ⊕ | .02 | 22 | YES | --- |
| ⊟ | .035 | 240 | YES | --- |
| ⊖ | .041 | 212 | YES | --- |
| ◫ | .073 | 4 | YES | --- |
| ⊕ | .1181 | 1 | YES | --- |
| □ | .1378 | 6 | YES | --- |

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SCH# B-2919
SPC# A-2920
ASM# B-2921

UNIVERSITY OF CHICAGO
ELECTRONICS DEVELOPMENT GROUP

TITLE
A-2920 Specification

SHEET 1 OF 1
DATE 02/03/2020
DRAWN TANG

B- 2920
REV 1.0